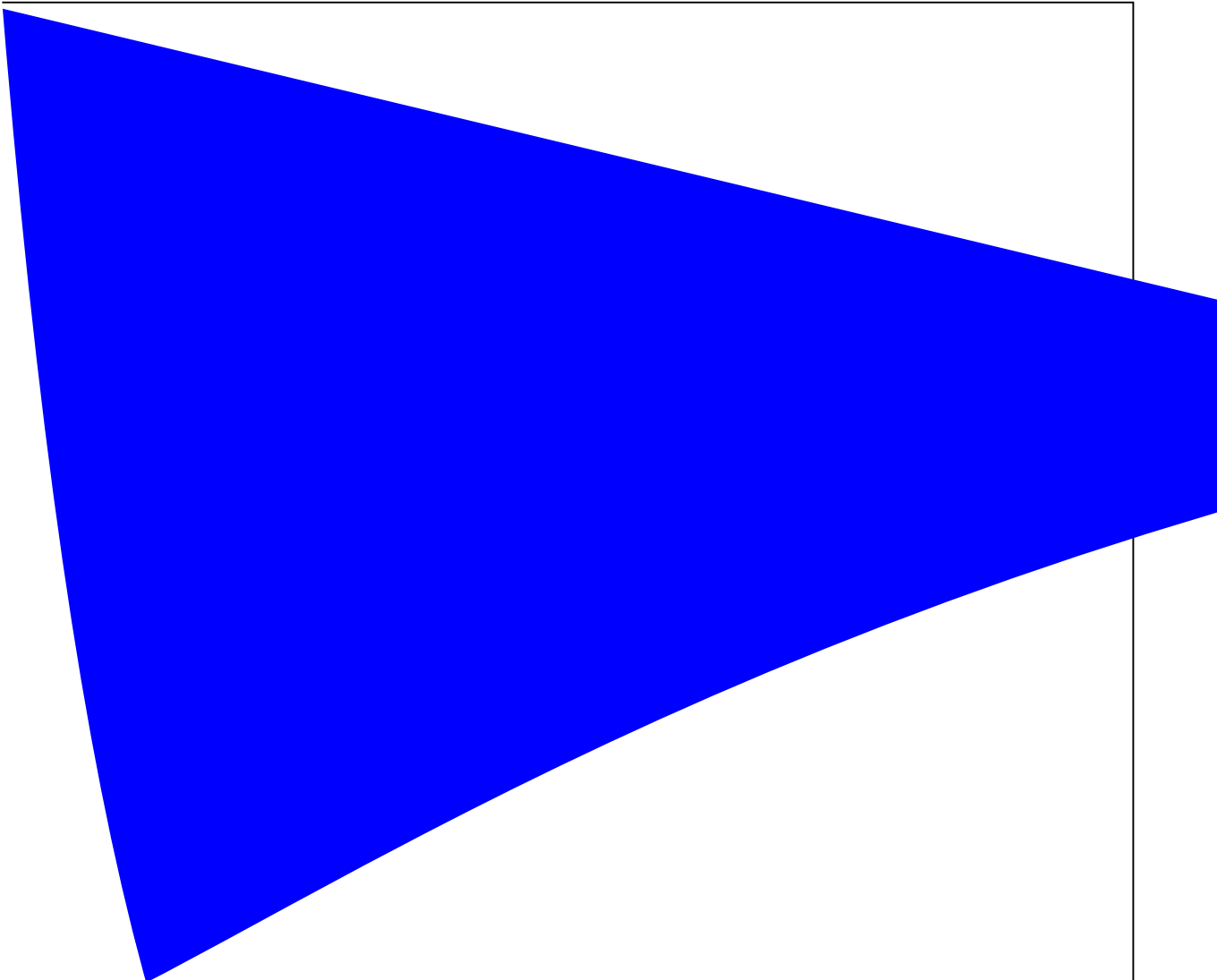


HT









## Photo Transistor Diode Specification

●Commodity: Photo Transistor

●Ic(on) Bin Code ( $V_{CE}=5V$ ,  $E_e=1mW/cm^2$ ,  $\lambda=940nm$ )

BIN CODE	Min. (mA)	Max. (mA)
X2	3.7	4.4
X3	4.4	5.3



## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

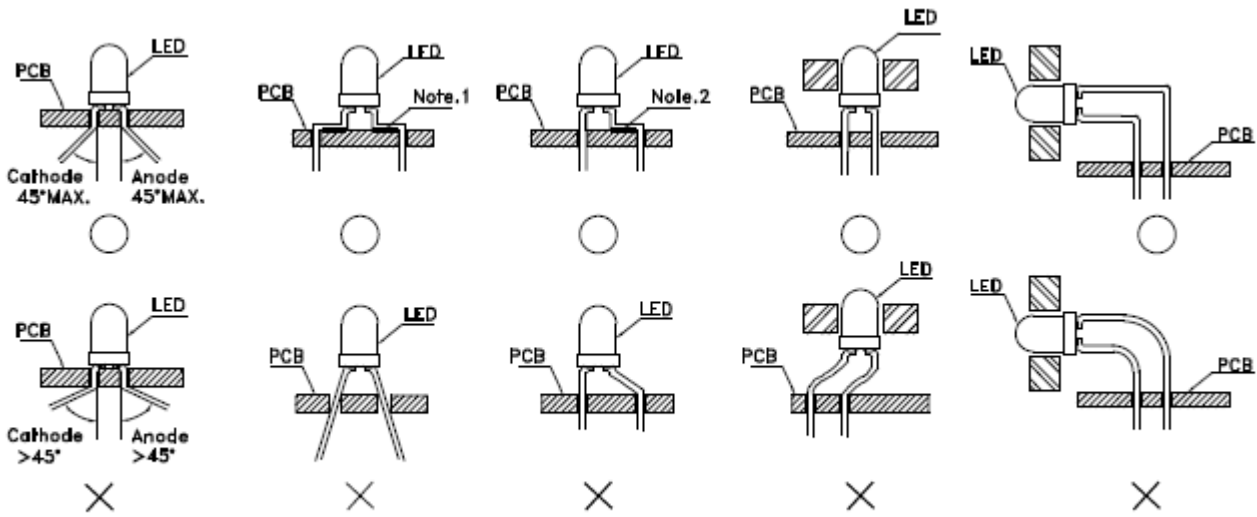


Fig. 1

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

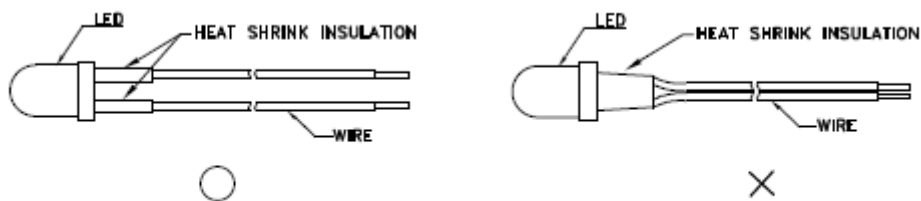


Fig. 2

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

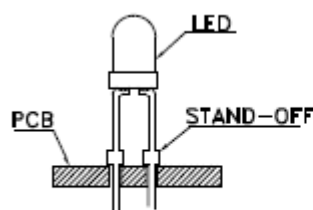


Fig. 3

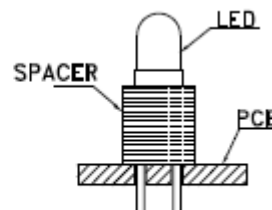
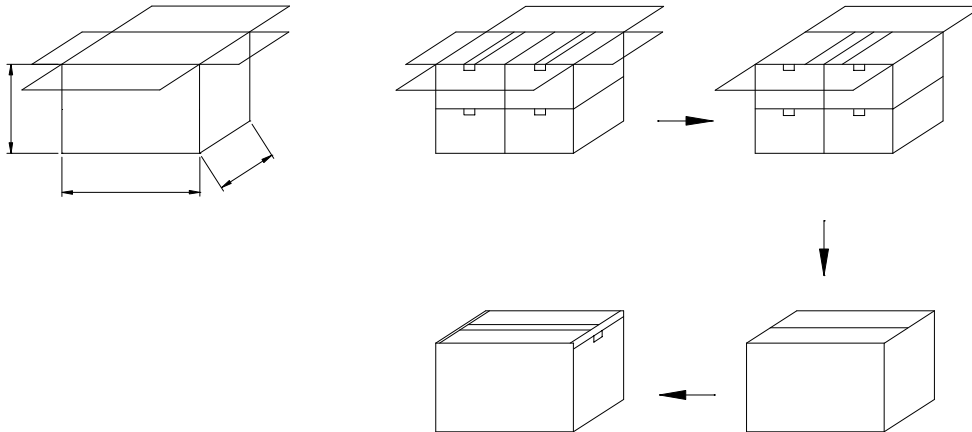
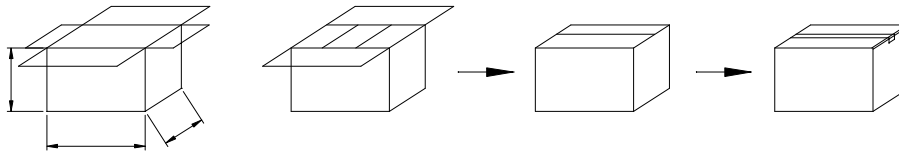
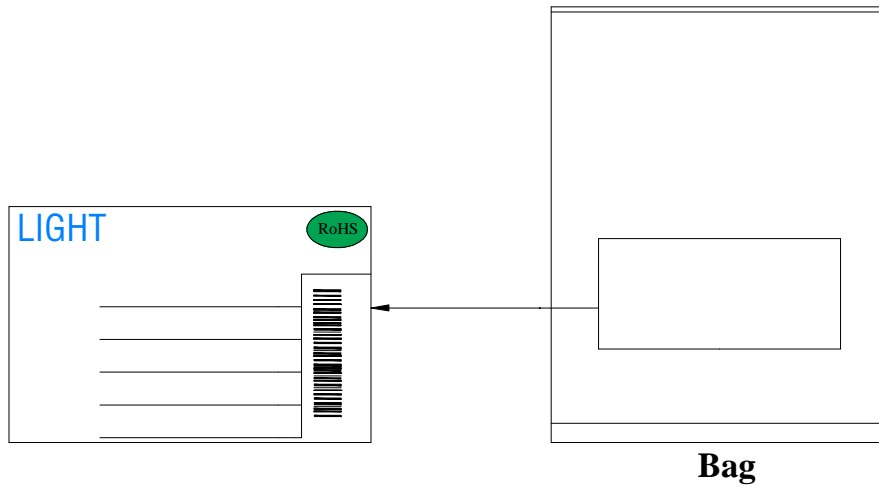


Fig. 4

PLACED



## PACKAGE



Bag minimum volume (pcs / Bag)	Bag volume (pcs / Bag)	Inner box volume (Bag / box)	Outer carton volume (Box / Carton)
500	1000	10	4